Features

- AEC-Q101 Qualified
- Halogen Free. "Green" Device (Note 1)
- Glass Passivated Chip Junction
- High Forward Surge Capability
- Epoxy Meets UL 94 V-0 Flammability Rating
- Moisture Sensitivity Level 1
- Lead Free Finish/RoHS Compliant (Note 2)("P" Suffix Designates RoHS Compliant. See Ordering Information)

2 Amp General Purpose Rectifier 50 to 1000 Volts

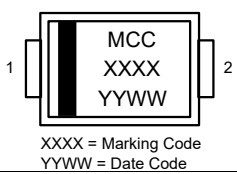
Maximum Ratings @ 25°C (Unless Otherwise Specified)

Parameter	Symbol	Value							Unit
		GS2A HE3-L	GS2B HE3-L	GS2D HE3-L	GS2G HE3-L	GS2J HE3-L	GS2K HE3-L	GS2M HE3-L	
Peak Repetitive Reverse Voltage	V_{RRM}	50	100	200	400	600	800	1000	V
Working Peak Reverse Voltage	V_{RWM}								
DC Blocking Voltage	V_R								
RMS Reverse Voltage	V_{RMS}	35	70	140	280	420	560	700	V
Average Rectified Forward Current @ T_L=100°C	$I_{F(AV)}$	2							A
Non-Repetitive Peak Surge Current @ 8.3ms Half Sine Wave	I_{FSM}	50							A
Non-Repetitive Peak Surge Current @ 1ms Square Wave		100							
Current Squared Time @1ms≤t≤8.3ms	I^2t	10.375							A^2s

Marking code

Part Number	Marking Code
GS2AHE3-L	GS2A
GS2BHE3-L	GS2B
GS2DHE3-L	GS2D
GS2GHE3-L	GS2G
GS2JHE3-L	GS2J
GS2KHE3-L	GS2K
GS2MHE3-L	GS2M

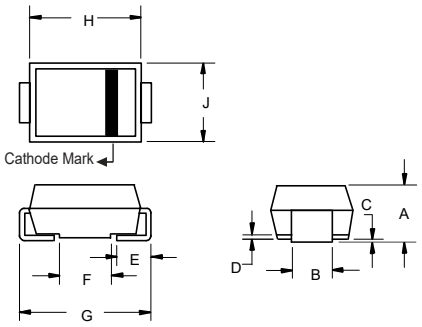
Internal Structure

Pin	Description	Simplified Outline	Graphic Symbol
1	Cathode	 XXXX = Marking Code YYWW = Date Code	
2	Anode		

Note: 1. Halogen free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

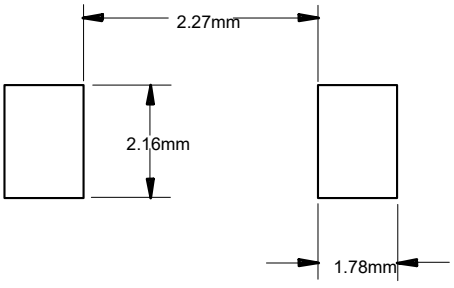
2. High temperature solder exemption applied, see EU directive annex 7a.

SMA (DO-214AC)



DIMENSIONS					
DIM	INCHES		MM		NOTE
	MIN	MAX	MIN	MAX	
A	0.075	0.096	1.90	2.44	
B	0.050	0.064	1.27	1.63	
C	0.002	0.008	0.051	0.203	
D	---	0.020	---	0.51	
E	0.030	0.060	0.76	1.52	
F	0.065	0.091	1.65	2.32	
G	0.189	0.220	4.80	5.59	
H	0.157	0.187	4.00	4.75	
J	0.090	0.115	2.25	2.92	

SUGGESTED SOLDER PAD LAYOUT



Thermal characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
T_J	Operating Junction Temperature Range		-55		150	°C
T_{stg}	Storage Temperature Range		-55		150	°C
$Rth_{(J-L)}$	Thermal Resistance from Junction to Lead	Note 1		22		°C/W
$Rth_{(J-A)}$	Thermal Resistance from Junction to Ambient	Note 1		75		°C/W

Note:
1.Mounted on P.C.B. with 8.0 mm x 8.0 mm copper pad areas.

Electrical Characteristics @ 25°C Unless Otherwise Specified

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Forward Voltage	V_F	I_F=2A;T_J=25°C			1.1	V
Reverse Current	I_R	at Rated V_R;T_J=25°C at Rated V_R;T_J=100°C at Rated V_R;T_J=125°C			5 50 100	μA
Junction Capacitance	C_J	V_R=4V;f=1MHz;T_J=25°C		18		pF
Reverse Recovery Time	t_{rr}	I_F=0.5A; I_R=1.0A; I_{rr}=0.25A;T_J=25°C		2.1	4	μS

Curve Characteristics

Fig. 1 - Forward Current Derating Curve

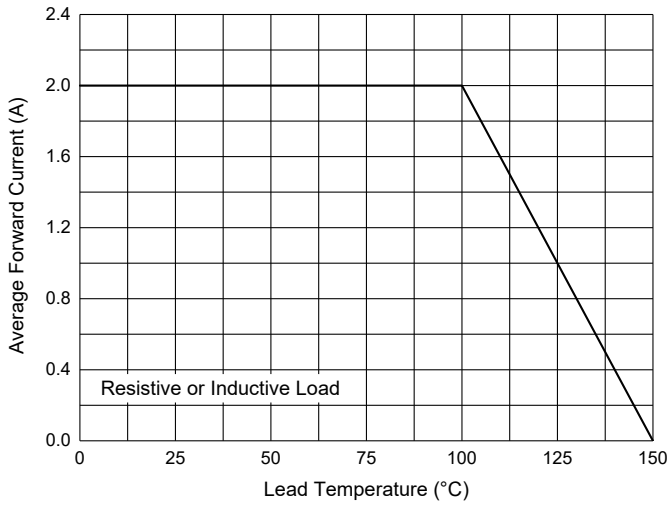


Fig. 2 - Maximum Non-Repetitive Peak Forward Surge Current

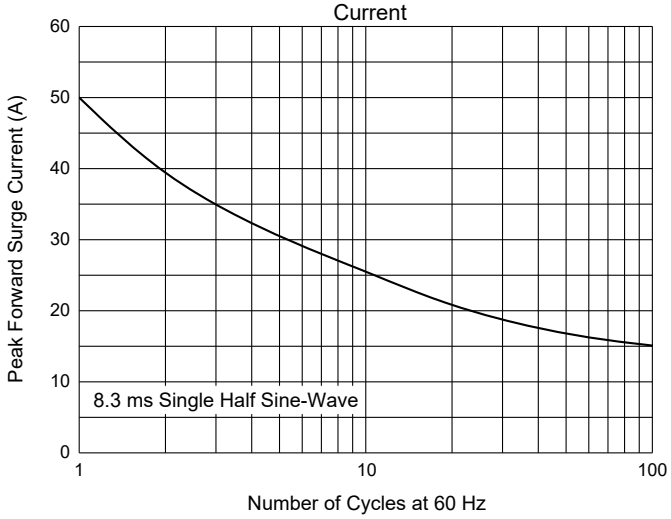


Fig. 3 - Typical Forward Characteristics

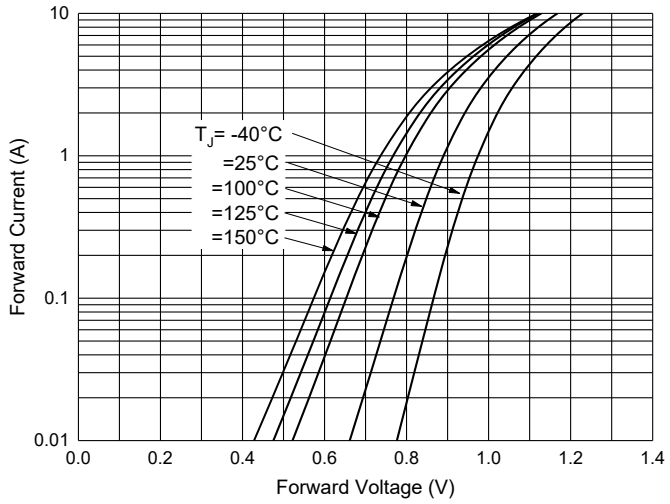


Fig. 4 - Typical Reverse Leakage Characteristics

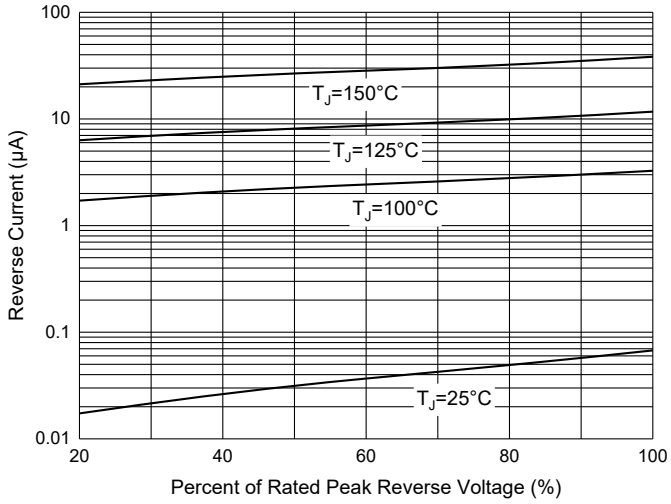
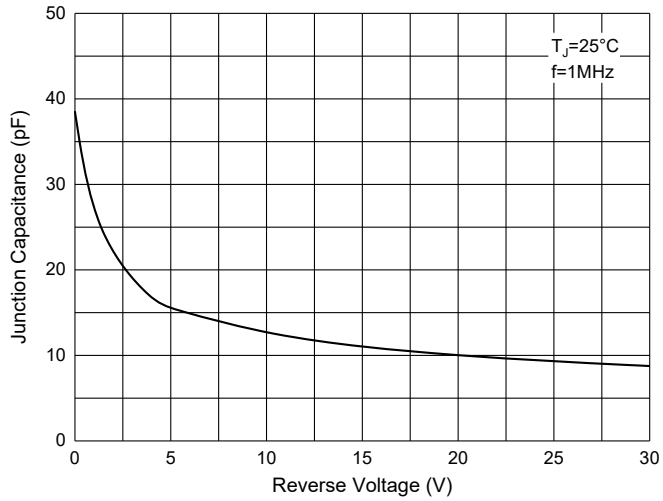


Fig. 5 - Typical Capacitance Characteristics



Ordering Information

Device	Packing
GS2AHE3-LTP ~ GS2MHE3-LTP	Tape&Reel:7.5Kpcs/Reel